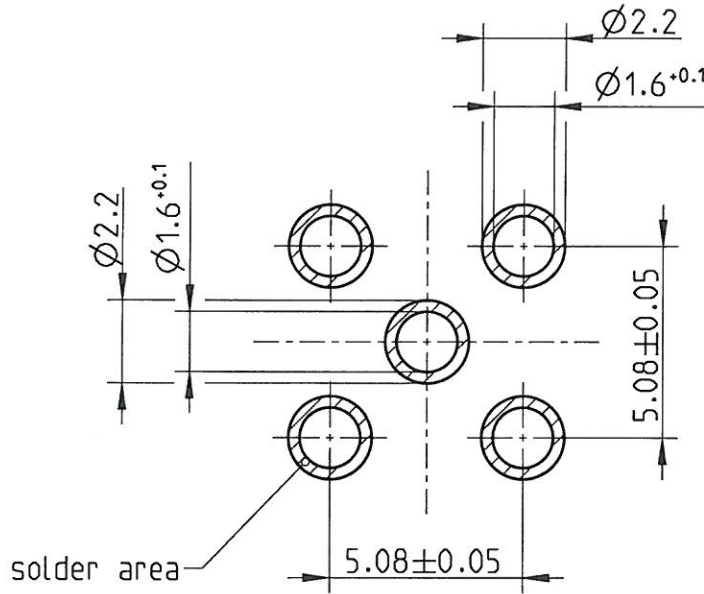


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Leiterplatten-Layout
PCB layout
B 30b



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formzahl: TCC_FB_05_PZ_AK_Einzelteil
Datei: A:\EPC\projekte\projekte\HFR\HFR_05_PZ_AK_Einzelteil.dwg
Version: 1.0

ISO-Projektion
Methode E
-METRIC-

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance ISO 2768 m-H		RN 006-01 dimensions <0,5 and symmetry		scale: 5:1	weight(g): surfacel(mm ²):
		date drawn 22.11.2004 check. 9.1.06 appr. 03.01.06		name A_Nobis <i>WZ</i> <i>Krautzb.</i>		title: Leiterplatten-Layout PCB layout	
		dimensioning incl. finish				part-no...: MB_30B	
b00	06-0011	A_Nobis	09.01.2006	distribution to: FE AZ QSM RMT . X			sheet: 1
a00	04-0709	A_Nobis	22.11.2004				of: 1
rev. change-no name date						remarks: .	